

1A, 200V-1000V High Efficient Surface Mount Rectifier

FEATURES

- AEC-Q101 qualified
- Glass passivated junction chip
- Ideal for automated placement
- Low power loss, high efficiency
- Fast switching for high efficiency
- Low profile package
- RoHS Compliant
- Halogen-free according to IEC 61249-2-21

APPLICATIONS

- Freewheeling
- Snubber
- DC/DC converters
- Automotive application

MECHANICAL DATA

- Case: Thin SMA
- Molding compound meets UL 94V-0 flammability rating
- Moisture sensitivity level: level 1, per J-STD-020
- Terminal: Matte tin plated leads, solderable per J-STD-002
- Meet JESD 201 class 2 whisker test
- Polarity: As marked
- Weight: 0.029g (approximately)

KEY PARAMETERS		
PARAMETER	VALUE	UNIT
I_F	1	A
V_{RRM}	200-1000	V
I_{FSM}	35	A
$T_{J\ MAX}$	150	°C
Package	Thin SMA	
Configuration	Single Die	


**HALOGEN
FREE**


Thin SMA



ABSOLUTE MAXIMUM RATINGS ($T_A = 25^\circ\text{C}$ unless otherwise noted)							
PARAMETER	SYMBOL	HS1DALH	HS1GALH	HS1JALH	HS1KALH	HS1MALH	UNIT
Marking code on the device		HS1DAH	HS1GAH	HS1JAH	HS1KAH	HS1MAH	
Repetitive peak reverse voltage	V_{RRM}	200	400	600	800	1000	V
Reverse voltage, total rms value	$V_{R(RMS)}$	140	280	420	560	700	V
Forward current	I_F	1					A
Surge peak forward current, single half sine-wave superimposed on rated load	$t = 8.3\text{ms}$	I_{FSM} 35					A
	$t = 1.0\text{ms}$	90					A
Junction temperature	T_J	-55 to +150					°C
Storage temperature	T_{STG}	-55 to +150					°C

THERMAL PERFORMANCE

PARAMETER	SYMBOL	TYP	UNIT
Junction-to-lead thermal resistance	$R_{\theta JL}$	29	°C/W
Junction-to-ambient thermal resistance	$R_{\theta JA}$	51	°C/W
Junction-to-case thermal resistance	$R_{\theta JC}$	22	°C/W

Thermal Performance Note: Units mounted on PCB (5mm x 5mm Cu pad test board)

ELECTRICAL SPECIFICATIONS ($T_A = 25^\circ\text{C}$ unless otherwise noted)

PARAMETER		CONDITIONS	SYMBOL	TYP	MAX	UNIT
Forward voltage ⁽¹⁾	HS1DALH	I _F = 0.5A, T _J = 25°C	V _F	0.80	-	V
		I _F = 1.0A, T _J = 25°C		0.85	1.00	V
		I _F = 0.5A, T _J = 125°C		0.65	-	V
		I _F = 1.0A, T _J = 125°C		0.71	0.80	V
	HS1GALH	I _F = 0.5A, T _J = 25°C		0.84	-	V
		I _F = 1.0A, T _J = 25°C		0.91	1.30	V
		I _F = 0.5A, T _J = 125°C		0.68	-	V
		I _F = 1.0A, T _J = 125°C		0.76	0.86	V
	HS1JALH	I _F = 0.5A, T _J = 25°C		0.92	-	V
		I _F = 1.0A, T _J = 25°C		1.02	1.70	V
		I _F = 0.5A, T _J = 125°C		0.73	-	V
		I _F = 1.0A, T _J = 125°C		0.83	1.02	V
	HS1KALH HS1MALH	I _F = 0.5A, T _J = 25°C		1.32	-	V
		I _F = 1.0A, T _J = 25°C		1.49	1.70	V
		I _F = 0.5A, T _J = 125°C		0.98	-	V
		I _F = 1.0A, T _J = 125°C		1.16	1.39	V
Reverse current @ rated V _R ⁽²⁾		T _J = 25°C	I _R	-	1	μA
		T _J = 125°C		-	35	μA
Reverse recovery time	HS1DALH HS1GALH	I _F = 0.5A, I _R = 1.0A, I _{rr} = 0.25A	t _{rr}	-	50	ns
	HS1JALH HS1KALH HS1MALH			-	75	ns
Junction capacitance	HS1DALH	1MHZ, V _R = 4.0V	C _J	20	-	pF
	HS1GALH			17	-	pF
	HS1JALH			13	-	pF
	HS1KALH HS1MALH			8	-	pF

Notes:

(1) Pulse test with $PW = 0.3\text{ms}$

(2) Pulse test with $PW = 30\text{ms}$

ORDERING INFORMATION

ORDERING CODE⁽¹⁾	PACKAGE	PACKING
HS1xALH M3G	Thin SMA	3,500 / 7" reel
HS1xALH M2G	Thin SMA	14,000 / 13" reel

Notes:

(1) "x" defines voltage from 200V(HS1DALH) to 1000V(HS1MALH)

CHARACTERISTICS CURVES

($T_A = 25^\circ\text{C}$ unless otherwise noted)

Fig.1 Forward Current Derating Curve

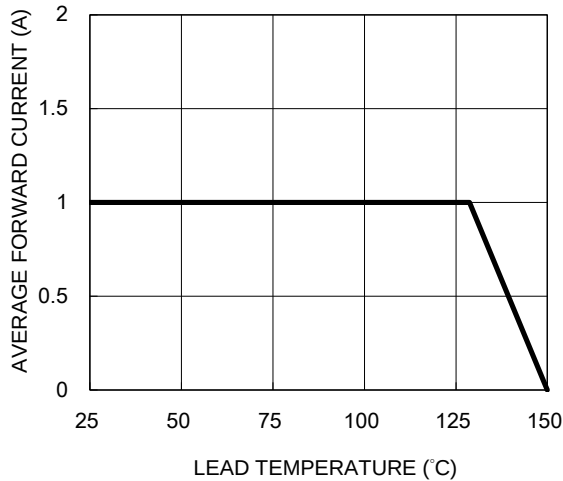


Fig.2 Typical Junction Capacitance

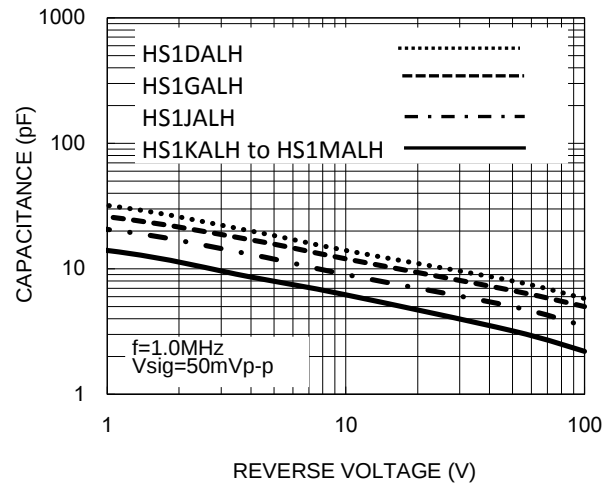


Fig.3 Typical Reverse Characteristics

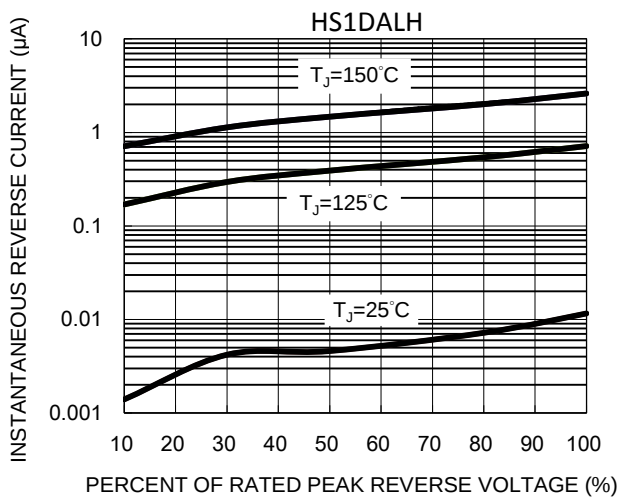


Fig.4 Typical Forward Characteristics

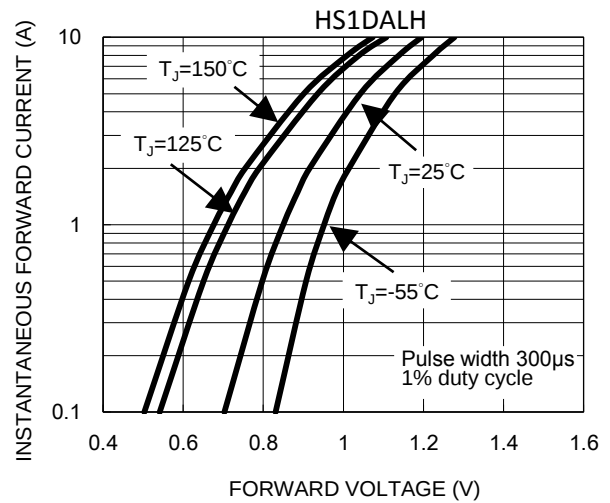


Fig.5 Typical Reverse Characteristics

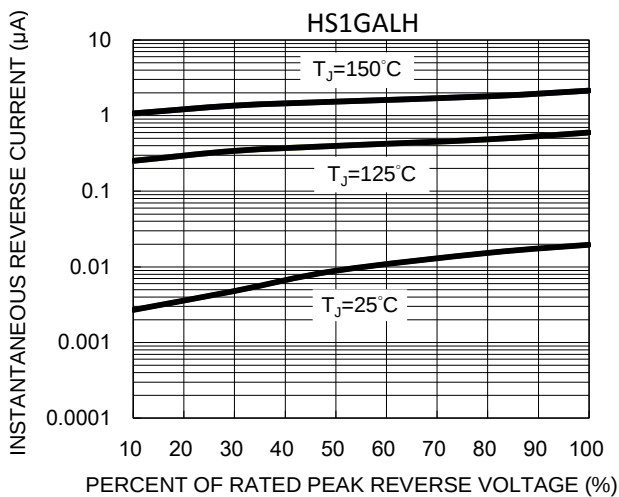
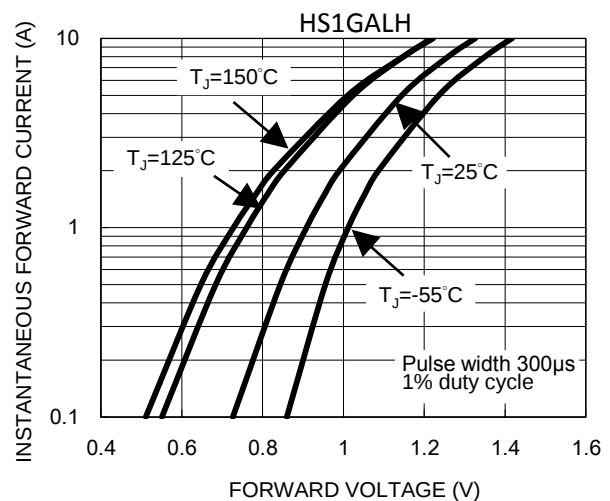


Fig.6 Typical Forward Characteristics



CHARACTERISTICS CURVES

($T_A = 25^\circ\text{C}$ unless otherwise noted)

Fig.7 Typical Reverse Characteristics

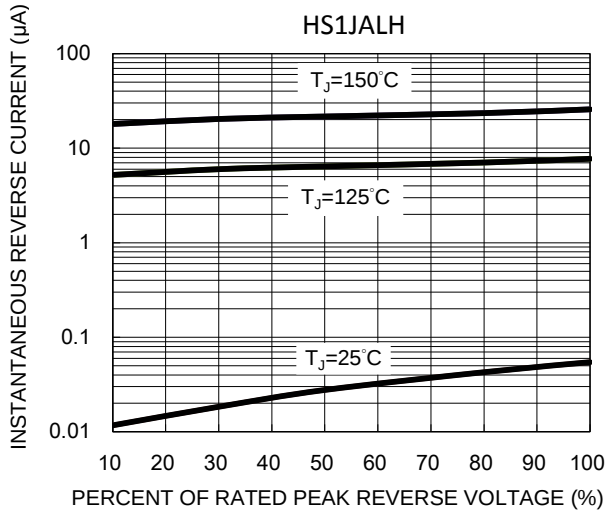


Fig.8 Typical Forward Characteristics

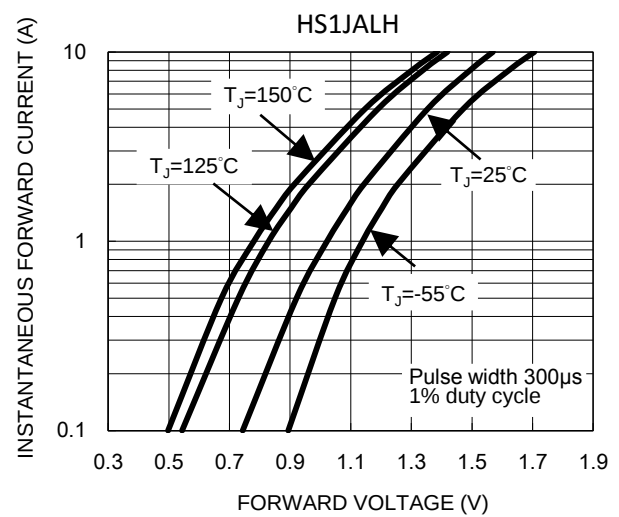


Fig.9 Typical Reverse Characteristics

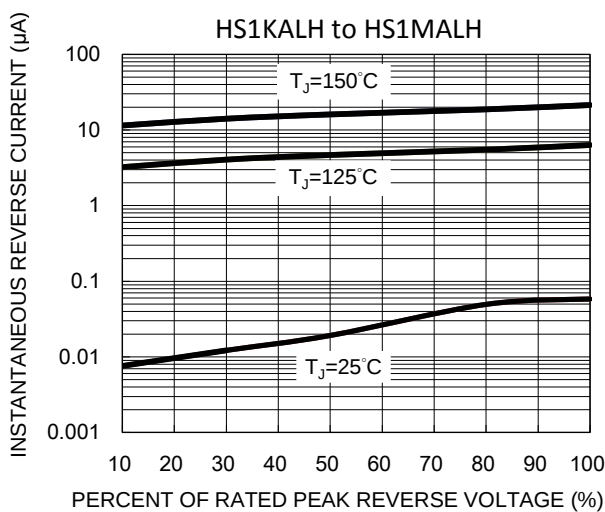


Fig.10 Typical Forward Characteristics

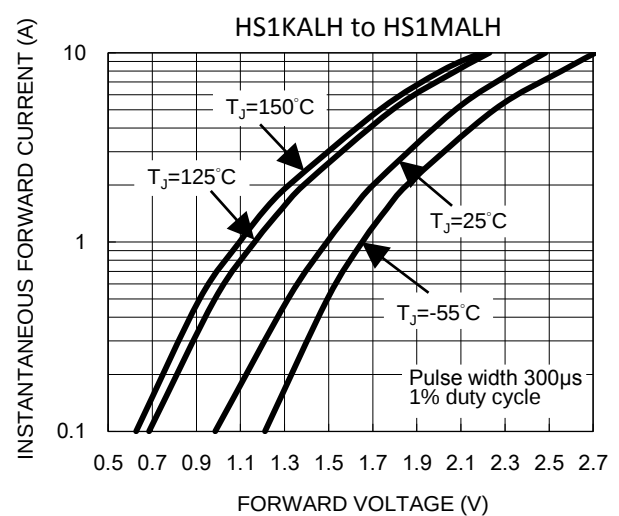
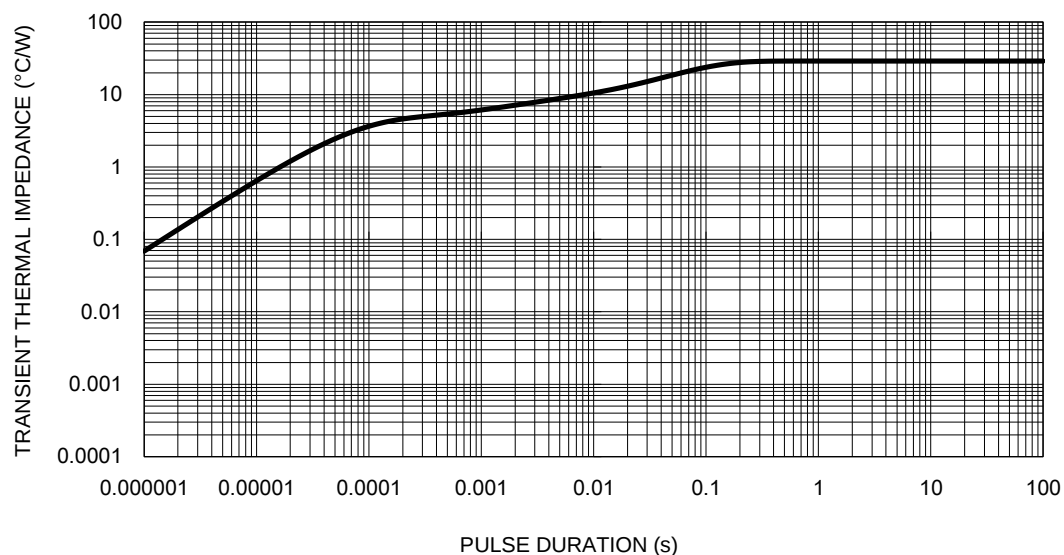
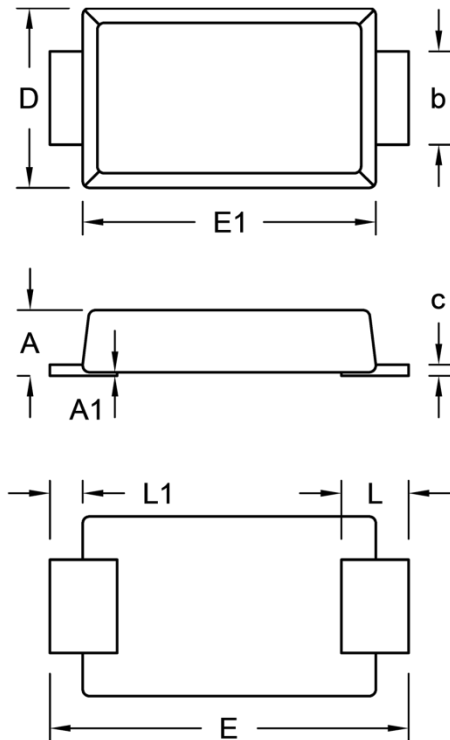


Fig.11 Typical Transient Thermal Impedance



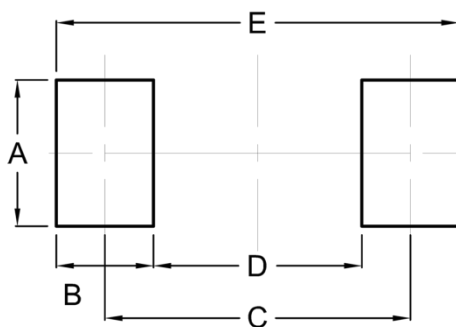
PACKAGE OUTLINE DIMENSIONS

Thin SMA



DIM.	Unit (mm)		Unit (inch)	
	Min.	Max.	Min.	Max.
A	0.90	1.00	0.035	0.039
A1	0.00	0.10	0.000	0.004
b	1.25	1.45	0.049	0.057
c	0.10	0.22	0.004	0.009
D	2.50	2.70	0.098	0.106
E	5.05	5.35	0.199	0.211
E1	4.15	4.35	0.163	0.171
L	0.75	1.20	0.030	0.047
L1	0.30	0.60	0.012	0.024

SUGGESTED PAD LAYOUT



Symbol	Unit (mm)	Unit (inch)
A	2.10	0.083
B	1.40	0.055
C	4.40	0.173
D	3.00	0.118
E	5.80	0.228

MARKING DIAGRAM



P/N = Marking Code
 YW = Date Code
 F = Factory Code

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